

In the claims:

Claim 1 (cancelled).

Claim 2 (currently amended) A ~~tin-silver based~~ lead-free solder ~~containing~~ consisting of 0.3 to 1% of zinc, ~~further containing~~ 8 to 10% by weight of indium (In) and 3 to 3.5% of silver and the balance of tin.

Claims 3 and 4 (cancelled).

Claim 5 (previously presented) A joint structure, comprising bodies to be joined are joined together by the tin-silver based lead-free solder of claim 2.

Claim 6 (previously presented) The joint structure of claim 5, wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

Claim 7 (previously presented) The joint structure of claim 6, wherein said electroless-plating layer is a Ni-P plating.

Claim 8 (cancelled).

Cancel Claim 9.

Claims 10 to 16(cancelled).